

AMPMODU | AMPMODU Headers

TE Internal #: 4-146490-0 PCB Mount Header, Vertical, Board-to-Board, 80 Position, 2.54 mm [.1 in] Centerline, Unshrouded, Gold, Through Hole - Solder, Signal, AMPMODU Headers

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PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical

Connector System: Board-to-Board

Number of Positions: **80**

Number of Rows: 2

Features

Product Type Features

PCB Connector Assembly Type

Connector System

Header Type

PCB Mount Header

Board-to-Board

Unshrouded

Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Stackable	Yes
PCB Mount Orientation	Vertical
Number of Positions	80
Number of Rows	2
Board-to-Board Configuration	Parallel
Electrical Characteristics	
Insulation Resistance	5000 MΩ
Body Features	
Primary Product Color	Black
Contact Features	
Contact Mating Area Length	8.38 mm[.33 in]
Mating Square Post Dimension	.64 mm[.025 in]

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	100 – 200 µin
Contact Shape & Form	Square
PCB Contact Termination Area Plating Material	Tin-Lead
Contact Base Material	Copper Alloy
Contact Mating Area Plating Material	Gold
Contact Mating Area Plating Material Thickness	.381 μm[15 μin]
Contact Type	Pin
Contact Current Rating (Max)	3 A
Termination Features	
Square Termination Post & Tail Dimension	.64 mm[.025 in]
Termination Post & Tail Length	2.77 mm[.109 in]
Termination Method to Printed Circuit Board	Through Hole - Solder
Mechanical Attachment	
Mating Alignment	Without
PCB Mount Retention	Without
PCB Mount Alignment	Without
Connector Mounting Type	Board Mount

Housing Features

Centerline (Pitch)	2.54 mm[.1 in]
Housing Material	Thermoplastic
Dimensions	
Row-to-Row Spacing	2.54 mm[.1 in]
Stack Height	7.62 mm[.3 in]
PCB Thickness (Recommended)	1.4 mm[.055 in]
Usage Conditions	
Operating Temperature Range	-65 – 125 °C[-85 – 257 °F]
Operating Temperature Range Operation/Application	-65 – 125 °C[-85 – 257 °F]
	-65 – 125 °C[-85 – 257 °F] None
Operation/Application	
Operation/Application Assembly Process Feature	None
Operation/Application Assembly Process Feature Circuit Application	None

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Packaging Features

Packaging Quantity	75
Packaging Type	Carton
Product Compliance For compliance documentation, visit the product page on TE.com>	
EU RoHS Directive 2011/65/EU	Not Compliant
EU ELV Directive 2000/53/EC	Compliant with Exemptions
China RoHS 2 Directive MIIT Order No 32, 2016	Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) SVHC > Threshold: Pb (13% in Component Part) Article Safe Usage Statements: Do not eat, drink or smoke when using this product. Wash thoroughly after handling. Recycle if possible and dispose of the article by following all applicable governmental regulations relevant to your geographic location.
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Wave solder capable to 240°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

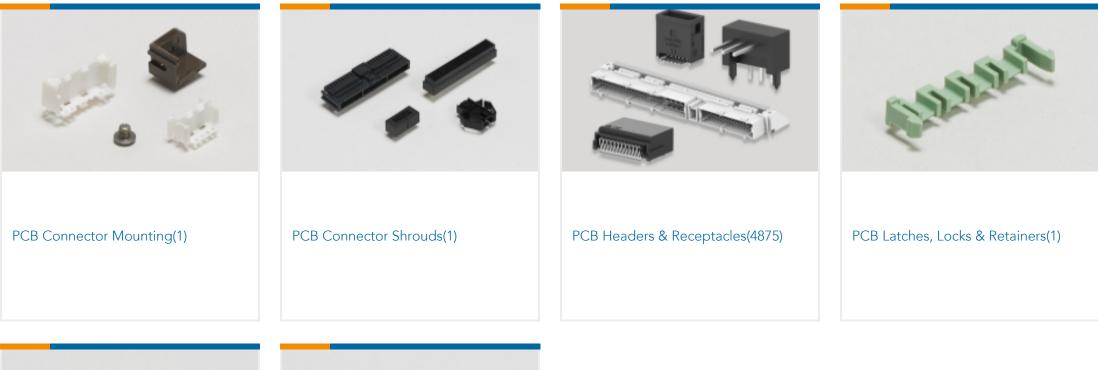
Compatible Parts

PCB Mount Header, Vertical, Board-to-Board, 80 Position, 2.54 mm [.1 in] Centerline, Unshrouded, Gold, Through Hole - Solder, Signal, AMPMODU Headers



TE Part # 4-146486-0 80 MODII HDR DRST UNSHRD STKG

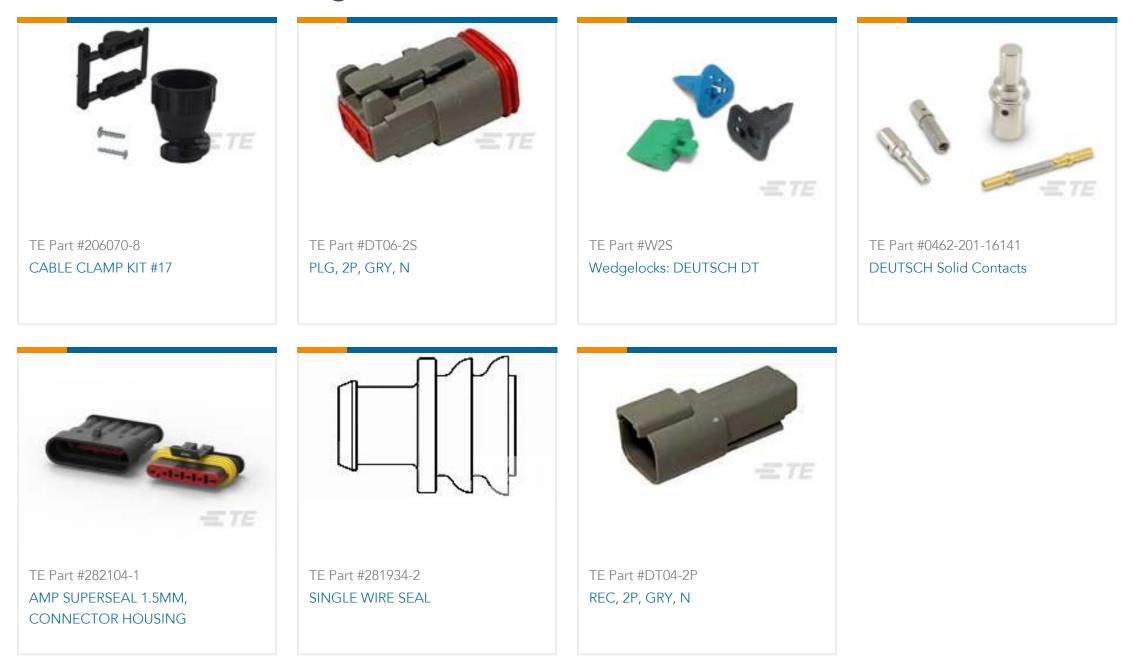
Also in the Series AMPMODU Headers





Wire-to-Board Connector Assemblies	Wire-to-Board Connector Contacts(65)
& Housings(5)	

Customers Also Bought



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Documents

Product Drawings 80 MODII HDR DRST UNSHRD STKG

English

Datasheets & Catalog Pages AMPMODU Interconnetion System

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English